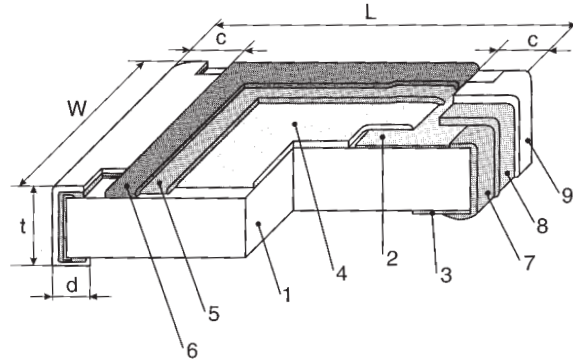
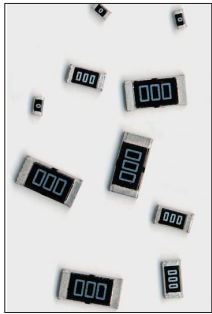


FLAT CHIP ZERO OHM JUMPER RK73Z



STRUCTURE

- 1 Ceramic substrate
- 2 Top termination (Ag Pd)
- 3 Bottom termination (Ag Pd)
- 4 Silver element
- 5 Glass layer
- 6 Protective layer
Epoxy: 1H...2B
Glass: 2E...3A
- 7 End termination (Ag Pd)
- 8 Diffusion barrier (Ni)
- 9 Solder plating



IDENTIFICATION

TYPE	COATING COLOR	MARKING
RK73Z 1H, RK73Z 1E	Green	None
RK73Z 1J	Black	White ("0")
RK73Z 2A ... RK73Z 3A		White ("000")

TYPE DESIGNATION (HOW TO ORDER)

Old Part No.	RK73Z	1J	TD
New Part No.	RK73Z	1J	TD
	PRODUCT CODE	STYLE	TERMINATION SURFACE MATERIAL
			T: Sn L: Sn/Pb
			TAPING*
			*Please see "PACKAGING"

FEATURES

- Silver element
- Anti-leaching nickel barrier terminations
- Also available with epoxy bondable, palladium silver terminations in sizes 0603 ... 2512
- Suitable for reflow and wave soldering

DIMENSIONS (mm)

SIZE	TYPE	L	W	c	d	t
0201	RK73Z 1H	0.6 ± 0.03	0.3 ± 0.03	0.1 ± 0.05	0.15 ± 0.05	0.23 ± 0.03
0402	RK73Z 1E	1.0 ^{+0.1} _{-0.05}	0.5 ± 0.05	0.2 ± 0.1	0.25 ^{+0.05} _{-0.1}	0.35 ± 0.05
0603	RK73Z 1J	1.6 ± 0.2	0.8 ± 0.1	0.3 ± 0.1	0.3 ± 0.1	0.45 ± 0.1
0805	RK73Z 2A	2.0 ± 0.2	1.25 ± 0.1	0.4 ± 0.2	0.3 ^{+0.2} _{-0.1}	0.5 ± 0.1
1206	RK73Z 2B	3.2 ± 0.2	1.6 ± 0.2	0.5 ± 0.3	0.4 ^{+0.2} _{-0.1}	0.6 ± 0.1
1210	RK73Z 2E	2.6 ± 0.2	2.6 ± 0.2			
2010	RK73Z 2H	5.0 ± 0.2	2.5 ± 0.2			
2512	RK73Z 3A	6.3 ± 0.2	3.1 ± 0.2			

RATING

SIZE	TYPE	CURRENT RATING	MAX. SURGE CURRENT*	RATED AMBIENT TEMPERATURE	MAX. RESISTANCE VALUE	OPERATING TEMPERATURE RANGE
NEW 0201	RK73Z 1H	0.5 A	1A	+ 70° C	50 mΩ	- 55° C ... + 125° C
0402	RK73Z 1E	1 A	2 A			
0603	RK73Z 1J					
0805	RK73Z 2A		5 A	+ 70° C	50 mΩ	- 55° C ... + 155° C
1206	RK73Z 2B					
1210	RK73Z 2E	2 A	10 A			
2010	RK73Z 2H			+ 70° C	50 mΩ	- 55° C ... + 125° C
2512	RK73Z 3A					

* Pulse duration < 1s